Value

(Typ.)

8

SFL-8 Dielectric

Method

TO220



Features & Benefits

- Thermal resistance 100μm, 0.08 °C-in²/W
- Product Thermal Conductivity of 8 W/m-K
 - (2oz Cu x 100µm SFL-8 x 1.5 Al)
- High Electrical Strength
- Lead-free solder compatible
- RoHS compliant and environmentally green
- Available as a laminated panel, RCC or prepreg
- Available on aluminum and copper base substrates
 - o Other substrates materials may be available.

TCLAD Metal Core PCB's (MCPCB's) minimize thermal impedance and conducts heat more efficiently than standard printed wiring boards (PWB's).

The differentiating technology of Thermal Clad resides in the dielectric. This datasheet highlights the performance characteristics of TCLAD SFL-8

Applications

- · High power density applications where achieving low thermal resistance is required, such as:
- LED Lighting
- Power conversion
- Motor drives
- Solid state relays

Configurations

Thickness mm (mil) **Base Metal**

• 5052 Aluminum 0.8 (32), 1.0 (40)*, 1.5 (59)*, 2.0 (80) 6061 Aluminum 0.8 (32), 1.0 (40)*, 1.5 (59)*, 2.0 (80) 1050 Aluminum 0.8 (32), 1.0 (40)*, 1.5 (59)*, 2.0 (80)

4045 Aluminum 1.5 (59), 2.0 (80)

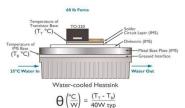
Copper C1100 1.0 (40)*, 1.5 (59)*, 2.0 (80)

Copper Foil Weight oz (thickness µm)

- ED Copper 1oz (35), 2oz (70), 3oz (105), 4oz (140), 6oz (210)
- RA 8oz (280), 10oz (350)
- Most common thicknesses
- Other thicknesses and alloys may be available. Please contact TCLAD sales department for more information.

We provide custom solutions for your applications. For Further inquiries, please contact your local sales agent or directly to TCLAD sales sales@tclad.com

Test Thermal Performance of Insulated Metal Substrate (IMS®) TO-220 Set-up



TCLAD

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Dielectric Thermal Conductivity W/m-K 2.75 ASTM D5470 100µm (4mil) °C-in²/W 0.08 **ASTM D5470** Resistance Thermal 100µm (4mil) °C/W 0.13 TO-220 Impedance **Electrical Properties** IPC-TM-650 Dielectric Constant 4.9 IPC-TM-650 1MHz 0.012 Dissipation 2.5.5.3 IPC-TM-650 Capacitance 100µm (4mil) рF 48.6 IPC-TM-650 2.5.17.1 Volume Resistivity 1013 Ω -cm IPC-TM-650 1015 Surface Resistivity Ω/sq 80µm (3.2mil) 4 Breakdown 100µm (4mil) **KVAC** 5 ASTM D149 Voltage 150µm (6mil) 7 **Mechanical Properties** Color Off-white Visual IPC TM-650 Peel Strength @ 25°C Kg/cm >1.4 IPC TM-650 Glass Transition (Tg) °C 150 2.4.25 IPC TM-650 CTE in X,Y/Z Axis <Tg µm/m°C 28 IPC TM-650 CTE in X,Y/Z Axis >Tg 35 µm/m°C 2.4.24.5 Youngs Modulus GPa ASTM D638 **Chemical Properties** IPC TM-650 % < 0.5 Water Vapor Retention 2.6.2.1 ASTM E595 Out-Gassing Total Mass Loss % < 0.1 Collect Volatile Condensable < 0.1 ASTM E595 Agency Ratings & Durability UL: E121882 UL Maximum Operating °C 140 UL 746 Temperature (MOT) V-0 UI 94 **UL Flammability** _ (CTI) 600 UL 746E **UL Comparative Tracking Index**

Item

Thermal Properties

Product Thermal Conductivity

Thickness

Unit

W/m-K